

CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS

Please replace the paragraph beginning at page 5, line 1 with the following entry:

FIG. 2 is a schematic and three-dimensional view of a heatsink stabilization plate according to a preferred embodiment of the present invention. In general, solid molecules could not completely fill all vacant space between objects such as heatsink 204 and a die. The unfilled vacant space, therefore, needs to be filled with a thermal pad 202. Preferably, the thermal pad 202 is disposed on the contact between the bottom of the heatsink 204 and the die. In this way the thermal pad 202 serves as a medium for heat conduction. Through such a medium, heat is transferred in a surface-to-surface mode instead of a point-to-point mode. To closely stick the thermal pad 202 on the die, a clip (not shown) is added to fasten the die onto a socket thereunder. However, note that the right portion of the heatsink 204 has cooling fins 204b more than the cooling fins 204a of the left portion of the heatsink 204. This difference makes the gravity center of the heatsink located on its right position. The gravity's center generates torque when the clip is used to fasten the die onto the socket, and the torque is usually a reason why thermal pad 202 cannot closely contact with the die. Without close contact, heat conduction from the die to the thermal pad 202 cannot be performed effectively.

Please replace the paragraph beginning at page 7, line 1 with the following entry:

However, it should be noted that the stabilization plate 308 cannot be too thick, since a thick stabilization plate may make the thermal pad and the die separate. A thick stabilization plate 408, a heatsink 304 and a die are schematically shown in FIG. 4. In contrast, FIG. 5 schematically shows a stabilization plate 508 having a thickness approximately equal to that of the die 300. In FIG. 5, it seems that a satisfied fastening result occurs. However, this is provided that the fastening force from the clip can be ignored. If the fastening force is considered, the stabilization plate 508 is still too thick. Note that the achievement wanted is to have stable contact of the thermal pad onto the die 300. The fastening force from the clip should be considered and this consideration tells us that the most preferable thickness of the stabilization plate 508 is slightly smaller than that of the die 300. Nevertheless, the thickness of the

stabilization plate 508 cannot be too small, since it would make the plate 508 has no contact with the chip under the die 300.
